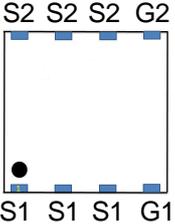


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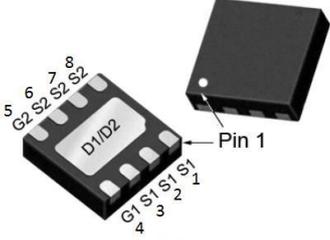
N+N-Channel Enhancement Mosfet

<p>General Description</p> <ul style="list-style-type: none"> • Low $R_{DS(ON)}$ • RoHS and Halogen-Free Compliant <p>Applications</p> <ul style="list-style-type: none"> • Load switch • PWM 	<p>Product Summary</p> <p>$V_{DS} = 20V$ $I_D = 55A$ $R_{DS(ON)} = 3.5 m\Omega (Typ.) @ V_{GS} = 4.5V$</p> <p>ESD protection</p> <p>100% UIS Tested 100% R_g Tested</p> 
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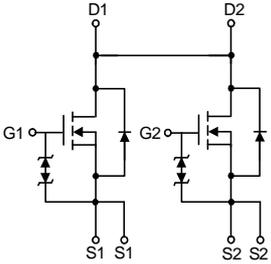


Marking: 18D03

DF:DFN3x3-8L



Pin 1



Absolute Maximum Ratings ($T_A = 25^\circ C$ Unless Otherwise Noted)				
Symbol	Parameter		Rating	Unit
Common Ratings ($T_A = 25^\circ C$ Unless Otherwise Noted)				
V_{DSS}	Drain-Source Voltage		20	V
V_{GSS}	Gate-Source Voltage		± 10	
T_J	Maximum Junction Temperature		150	$^\circ C$
T_{STG}	Storage Temperature Range		-55 to 150	
I_S	Diode Continuous Forward Current	$T_C = 25^\circ C$	55	A
I_D^a	Continuous Drain Current	$T_C = 25^\circ C$	55	A
		$T_C = 100^\circ C$	28	
I_{DM}^b	Pulsed Drain Current	$T_C = 25^\circ C$	175	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	Steady State	3.5	$^\circ C/W$
P_D^c	Maximum Power Dissipation	$T_A = 25^\circ C$	1.6	W
		$T_A = 70^\circ C$	1	
$R_{\theta JA}^d$	Thermal Resistance-Junction to Ambient	Steady State	78	$^\circ C/W$
I_{AS}^e	Avalanche Current, Single pulse ($L = 0.1mH$)		45	A
E_{AS}^e	Avalanche Energy, Single pulse ($L = 0.1mH$)		100	mJ

Note a: Package is limited by 50A
 Note b: Pulse width limited by max. junction temperature.
 Note c: $R_{\theta JA}$ steady state=999s.
 Note d: $R_{\theta JA}$ steady state=999s. $R_{\theta JA}$ is measured with the device mounted on 1in2, Fr-4 board with 2oz.Copper.
 Note e: UIS tested and pulse width limited by maximum junction temperature $150^\circ C$ (initial temperature $T_J = 25^\circ C$).

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N+N-Channel Enhancement Mosfet
Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

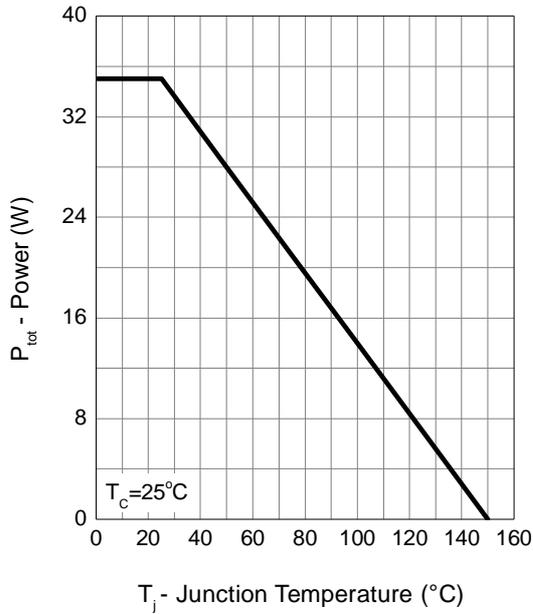
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu A$	20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=14.4V, V_{GS}=0V$ $T_J=85^\circ\text{C}$	-	-	1	μA
			-	-	30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	0.5	0.7	1	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 10V, V_{DS}=0V$	-	-	± 10	μA
$R_{DS(ON)}^g$	Drain-Source On-state Resistance	$V_{GS}=4.5V, I_{DS}=13.5A$	-	3.5	4.4	$m\Omega$
		$V_{GS}=2.5V, I_{DS}=10A$	-	4.5	6	
Gfs	Forward Transconductance	$V_{DS}=5V, I_{DS}=10A$	-	34	-	S
Diode Characteristics						
V_{SD}^d	Diode Forward Voltage	$I_{SD}=2A, V_{GS}=0V$	-	0.7	1.1	V
t_{rr}	Reverse Recovery Time	$I_{SD}=13.5A,$	-	18	-	ns
Q_{rr}	Reverse Recovery Charge	$di_{SD}/dt=100A/\mu s$	-	6.2	-	nC
Dynamic Characteristics^g						
R_G	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, f=1MHz$	-	2	3.6	Ω
C_{iss}	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=10V,$ Frequency=1.0MHz	-	3775		pF
C_{oss}	Output Capacitance		-	730		
C_{rss}	Reverse Transfer Capacitance		-	525		
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=10V, R_L=10\Omega,$ $I_{DS}=1A, V_{GEN}=10V,$ $R_G=6\Omega$	-	14	26	ns
t_r	Turn-on Rise Time		-	14.5	27	
$t_{d(OFF)}$	Turn-off Delay Time		-	130	234	
t_f	Turn-off Fall Time		-	70	126	
Gate Charge Characteristics^g						
Q_g	Total Gate Charge	$V_{DS}=10V, V_{GS}=4.5V,$ $I_{DS}=13.5A$	-	35	50	nC
Q_{gs}	Gate-Source Charge		-	4.7	-	
Q_{gd}	Gate-Drain Charge		-	11.5	-	

 Note f: Pulse test; pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

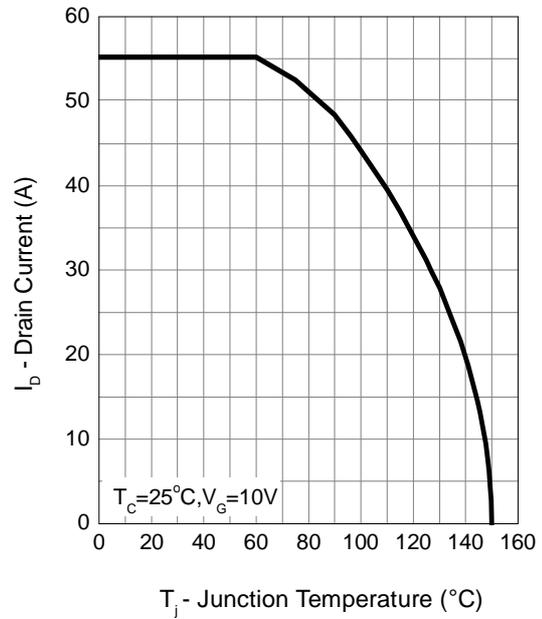
Note g: Guaranteed by design, not subject to production testing.

Typical Performance Characteristics

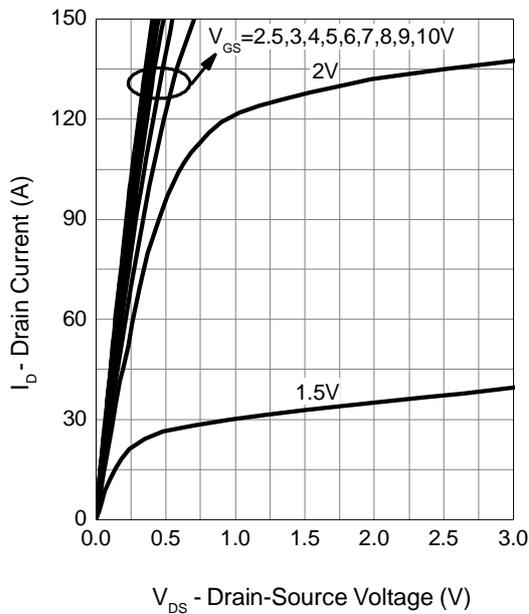
Power Dissipation



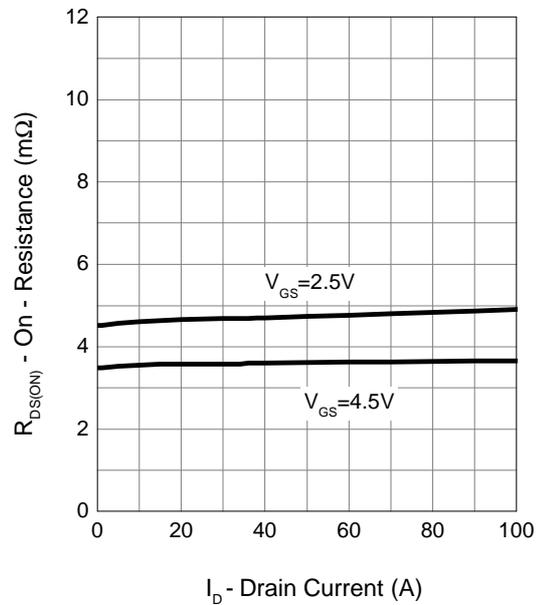
Drain Current



Output Characteristics



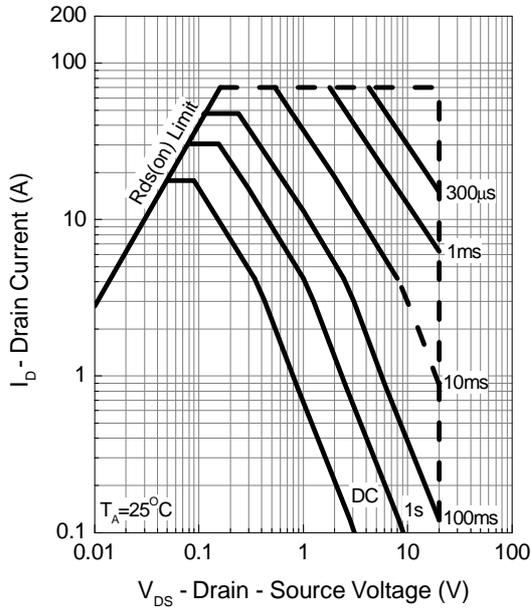
Drain-Source On Resistance



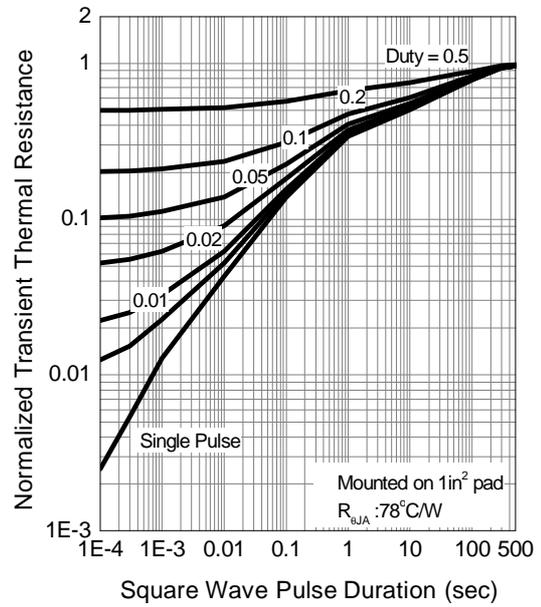
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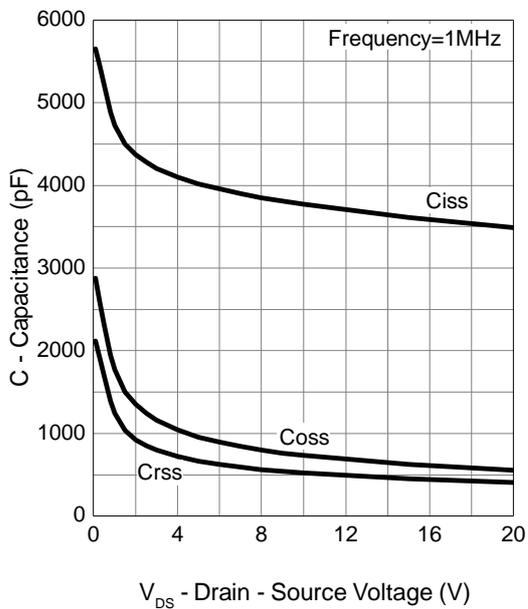
Safe Operation Area



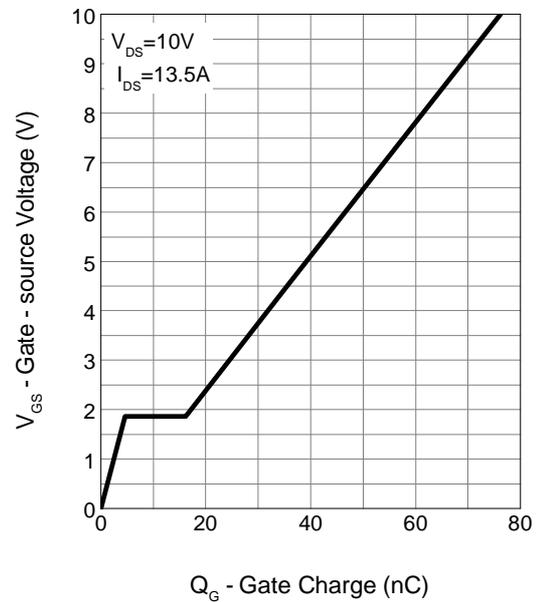
Thermal Transient Impedance



Capacitance



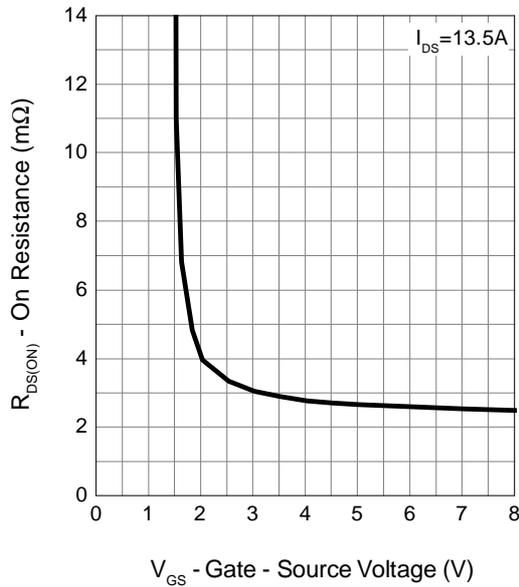
Gate Charge



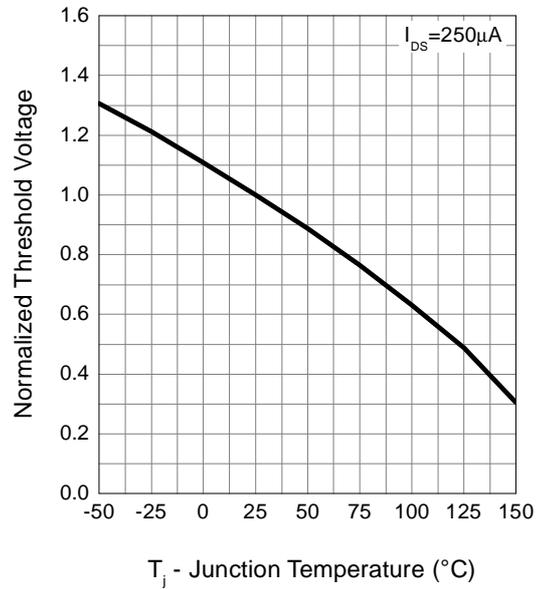
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N+N-Channel Enhancement Mosfet

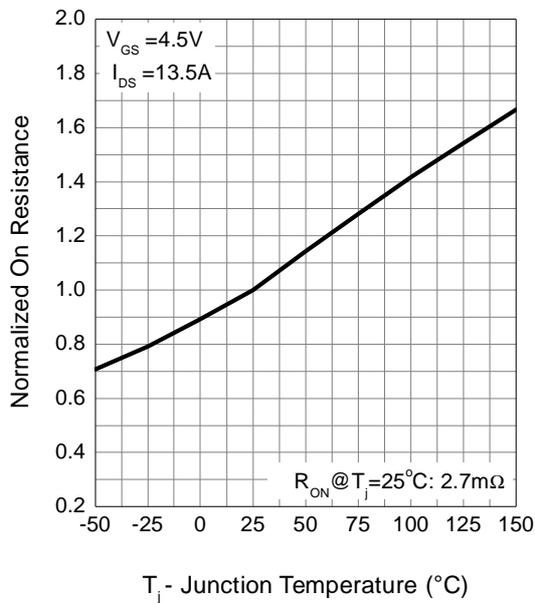
Gate-Source On Resistance



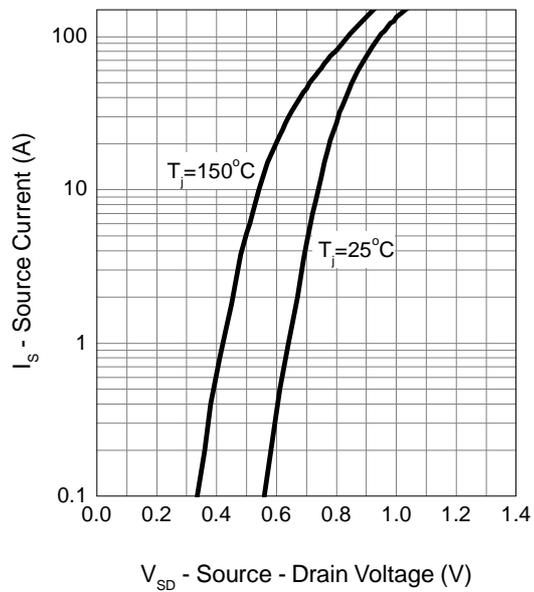
Gate Threshold Voltage



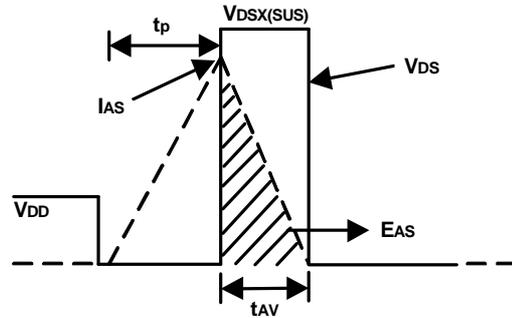
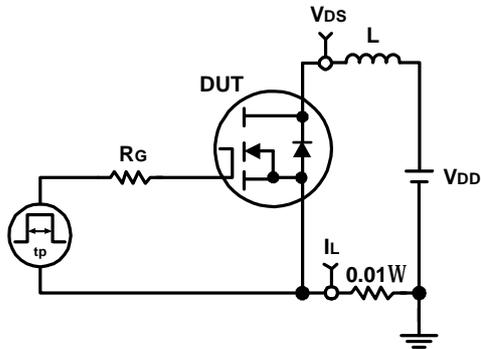
Drain-Source On Resistance



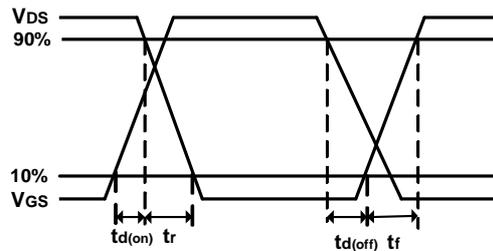
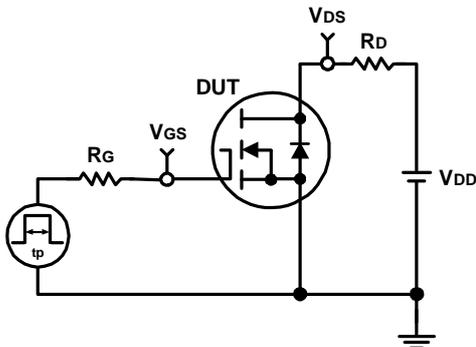
Source-Drain Diode Forward



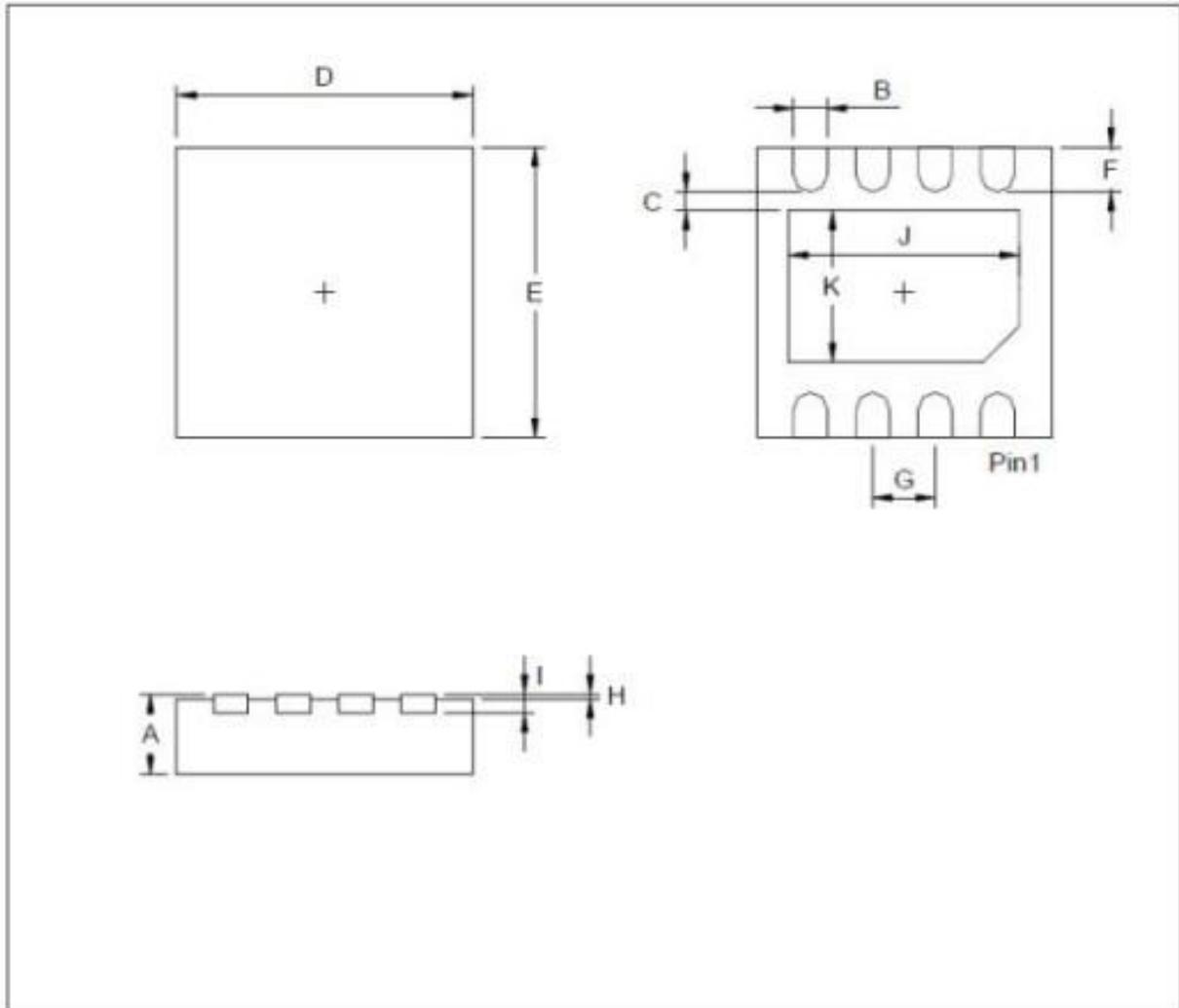
Avalanche Test Circuit and Waveforms



Switching Time Test Circuit and Waveforms



Package Mechanical Data:DFN3x3-8L



Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	0.7		0.8	I		0.203	
B	0.25		0.35	J	2.2		2.4
C	0.2			K	1.4		1.6
D	2.924		3.076				
E	2.924		3.076				
F	0.324		0.476				
G		0.65					
H	0		0.05				